

FMG1G100US60H

Molding Type Module

General Description

Fairchild's Insulated Gate Bipolar Transistor (IGBT) power modules provide low conduction and switching losses as well as short circuit ruggedness. They are designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

Features

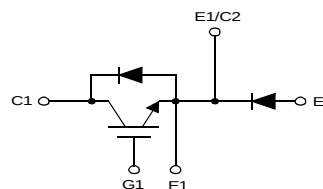
- UL Certified No. E209204
- Short Circuit rated 10us @ $T_C = 100^\circ\text{C}$, $V_{GE} = 15\text{V}$
- High Speed Switching
- Low Saturation Voltage : $V_{CE(sat)} = 2.2\text{V}$ @ $I_C = 100\text{A}$
- High Input Impedance
- Fast & Soft Anti-Parallel FWD

Application

- AC & DC Motor Controls
- General Purpose Inverters
- Robotics
- Servo Controls
- UPS



Package Code : 7PM-GA



Internal Circuit Diagram

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Description	FMG1G100US60H	Units
V_{CES}	Collector-Emitter Voltage	600	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C = 25^\circ\text{C}$	100	A
$I_{CM(1)}$	Pulsed Collector Current	200	A
I_F	Diode Continuous Forward Current @ $T_C = 100^\circ\text{C}$	100	A
I_{FM}	Diode Maximum Forward Current	200	A
T_{SC}	Short Circuit Withstand Time @ $T_C = 100^\circ\text{C}$	10	us
P_D	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$	400	W
T_J	Operating Junction Temperature	-40 to +150	$^\circ\text{C}$
T_{stg}	Storage Temperature Range	-40 to +125	$^\circ\text{C}$
V_{iso}	Isolation Voltage @ AC 1minute	2500	V
Mounting Torque	Power Terminals Screw : M5	2.0	N.m
	Mounting Screw : M5	2.0	N.m

Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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Off Characteristics

BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250μA	600	--	--	V
ΔBV _{CES} /ΔT _J	Temperature Coeff. of Breakdown Voltage	V _{GE} = 0V, I _C = 1mA	--	0.6	--	V/°C
I _{CES}	Collector Cut-Off Current	V _{CE} = V _{CES} , V _{GE} = 0V	--	--	250	μA
I _{GES}	G-E Leakage Current	V _{GE} = V _{GES} , V _{CE} = 0V	--	--	± 100	nA

On Characteristics

V _{GE(th)}	G-E Threshold Voltage	V _{GE} = 0V, I _C = 100mA	5.0	6.0	8.5	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 100A, V _{GE} = 15V	--	2.2	2.8	V

Dynamic Characteristics

C _{ies}	Input Capacitance	V _{CE} = 30V, V _{GE} = 0V, f = 1MHz	--	10840	--	pF
C _{oes}	Output Capacitance		--	963	--	pF
C _{res}	Reverse Transfer Capacitance		--	228	--	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{CC} = 300 V, I _C = 100A, R _G = 2.4Ω, V _{GE} = 15V Inductive Load, T _C = 25°C	--	25	--	ns
t _r	Rise Time		--	50	--	ns
t _{d(off)}	Turn-Off Delay Time		--	80	--	ns
t _f	Fall Time		--	110	200	ns
E _{on}	Turn-On Switching Loss		--	1.6	--	mJ
E _{off}	Turn-Off Switching Loss		--	2.4	--	mJ
E _{ts}	Total Switching Loss	V _{CC} = 300 V, I _C = 100A, R _G = 2.4Ω, V _{GE} = 15V Inductive Load, T _C = 125°C	--	4.0	--	mJ
t _{d(on)}	Turn-On Delay Time		--	25	--	ns
t _r	Rise Time		--	60	--	ns
t _{d(off)}	Turn-Off Delay Time		--	80	--	ns
t _f	Fall Time		--	240	--	ns
E _{on}	Turn-On Switching Loss		--	1.7	--	mJ
E _{off}	Turn-Off Switching Loss	V _{CC} = 300 V, V _{GE} = 15V @ T _C = 100°C	--	4.3	--	mJ
E _{ts}	Total Switching Loss		--	6.0	--	mJ
T _{sc}	Short Circuit Withstand Time		10	--	--	us
Q _g	Total Gate Charge	V _{CE} = 300 V, I _C = 100A, V _{GE} = 15V	--	425	500	nC
Q _{ge}	Gate-Emitter Charge		--	80	--	nC
Q _{gc}	Gate-Collector Charge		--	200	--	nC

Electrical Characteristics of DIODE T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Units
V _{FM}	Diode Forward Voltage	I _F = 100A	T _C = 25°C	--	1.9	2.8	V
			T _C = 100°C	--	1.8	--	
t _{rr}	Diode Reverse Recovery Time	I _F = 100A di / dt = 200 A/us	T _C = 25°C	--	90	130	ns
			T _C = 100°C	--	130	--	
I _{rr}	Diode Peak Reverse Recovery Current		T _C = 25°C	--	9	12	A
			T _C = 100°C	--	12	--	
Q _{rr}	Diode Reverse Recovery Charge		T _C = 25°C	--	405	790	nC
			T _C = 100°C	--	780	--	

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
R _{θJC}	Junction-to-Case (IGBT Part, per 1/2 Module)	--	0.31	°C/W
R _{θJC}	Junction-to-Case (DIODE Part, per 1/2 Module)	--	0.7	°C/W
R _{θCS}	Case-to-Sink (Conductive grease applied)	0.05	--	°C/W
Weight	Weight of Module	--	190	g

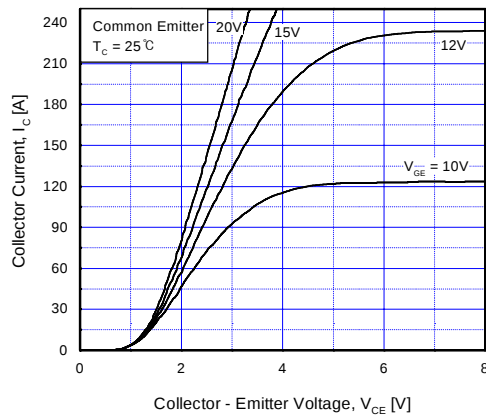


Fig 1. Typical Output Characteristics

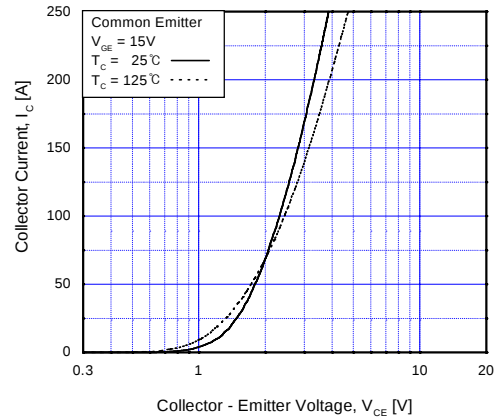


Fig 2. Typical Saturation Voltage Characteristics

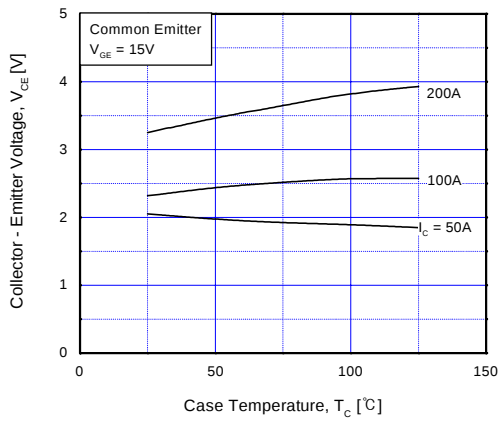


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

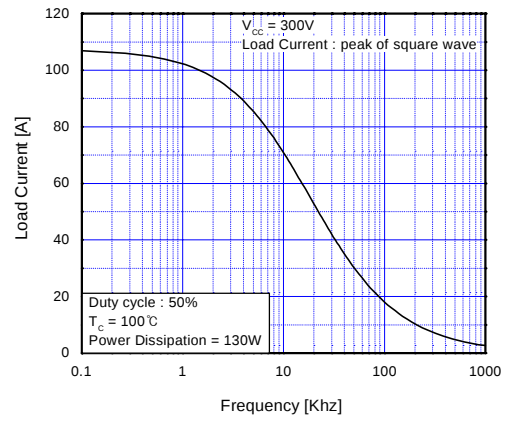


Fig 4. Load Current vs. Frequency

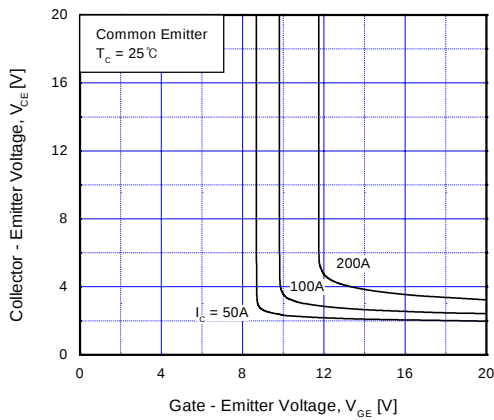


Fig 5. Saturation Voltage vs. V_{GE}

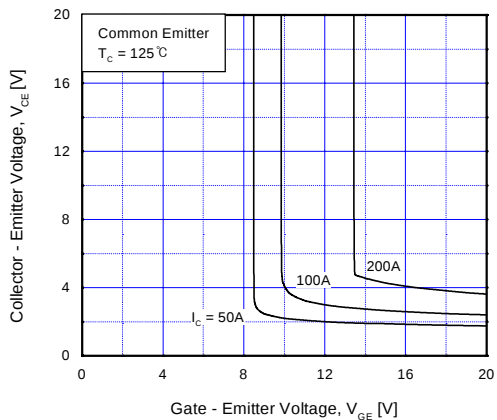


Fig 6. Saturation Voltage vs. V_{GE}

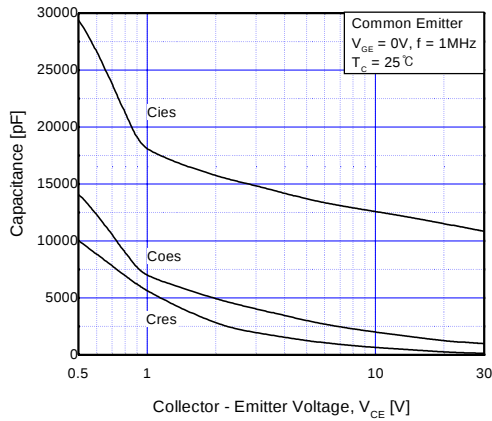


Fig 7. Capacitance Characteristics

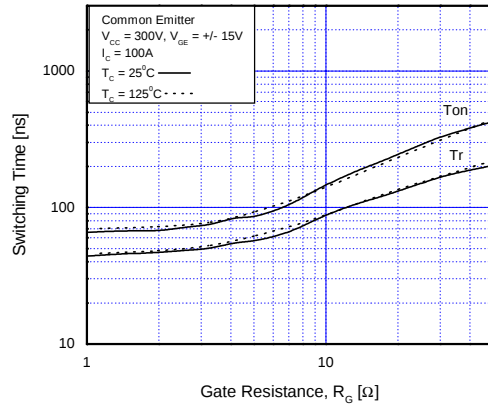


Fig 8. Turn-On Characteristics vs. Gate Resistance

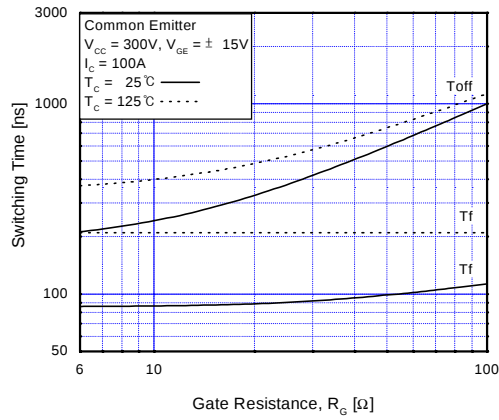


Fig 9. Turn-Off Characteristics vs. Gate Resistance

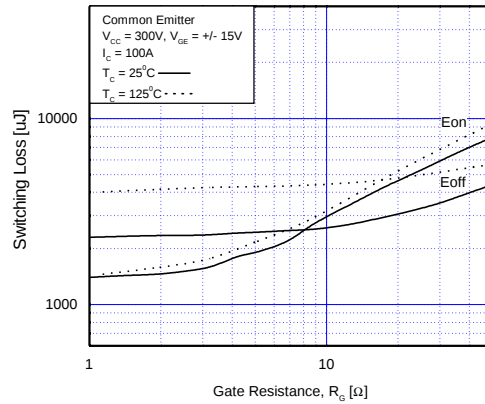


Fig 10. Switching Loss vs. Gate Resistance

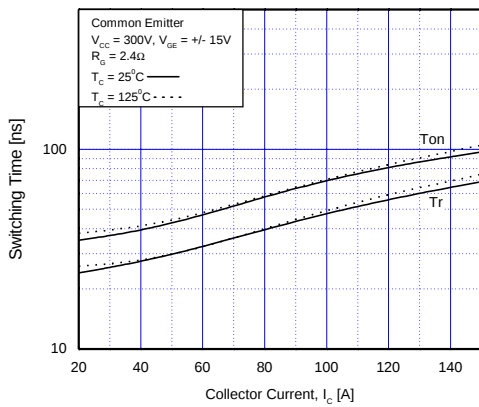


Fig 11. Turn-On Characteristics vs. Collector Current

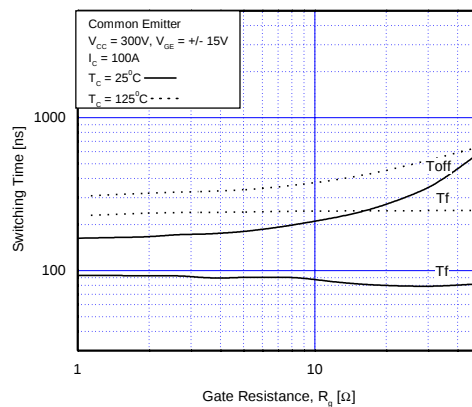


Fig 12. Turn-Off Characteristics vs. Collector Current

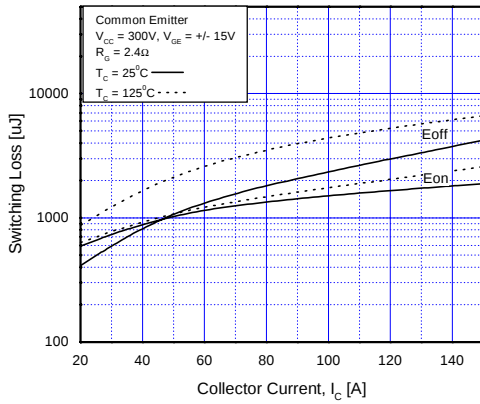


Fig 13. Switching Loss vs. Collector Current

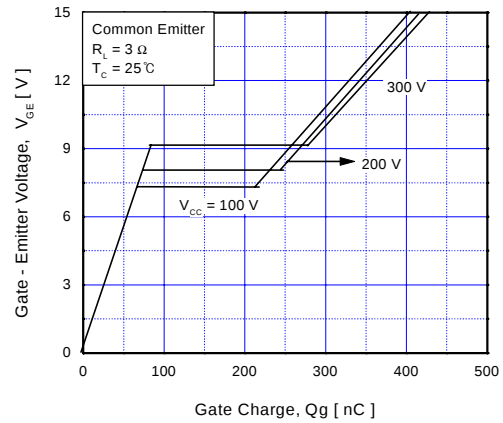


Fig 14. Gate Charge Characteristics

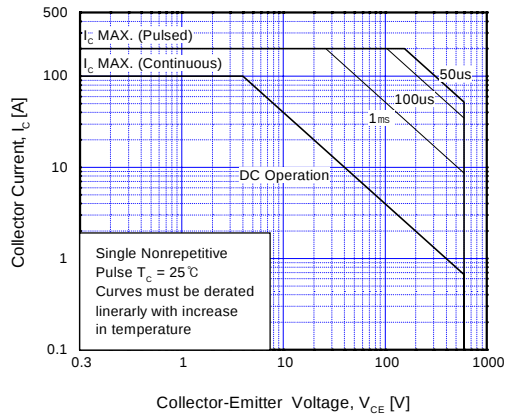


Fig 15. SOA Characteristics

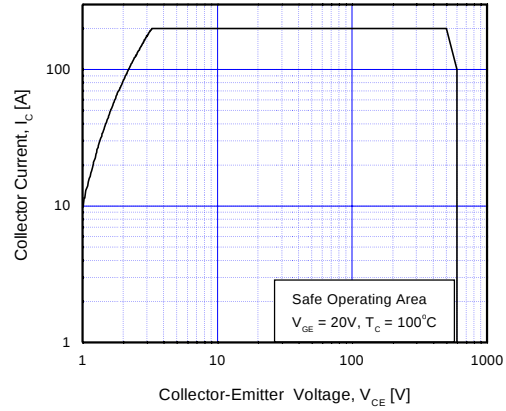


Fig 16. Turn-Off SOA Characteristics

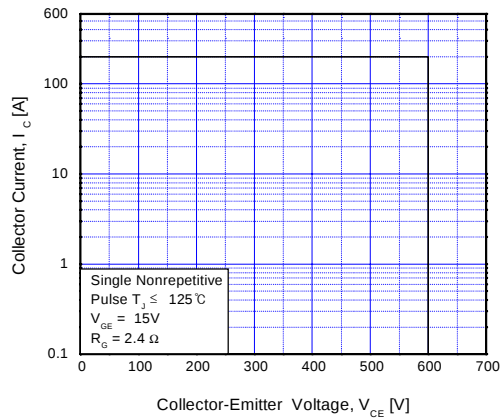


Fig 17. RBSOA Characteristics

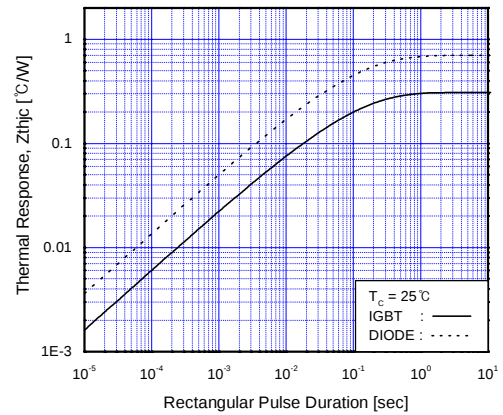


Fig 18. Transient Thermal Impedance

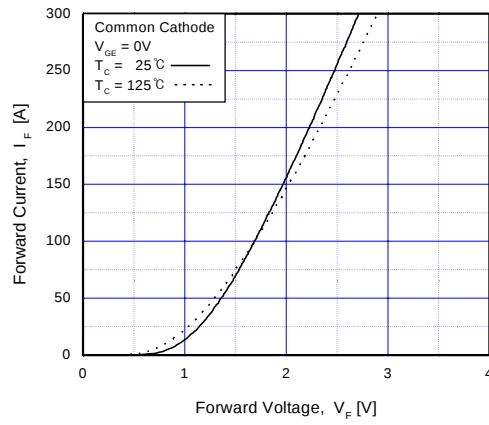


Fig 19. Forward Characteristics

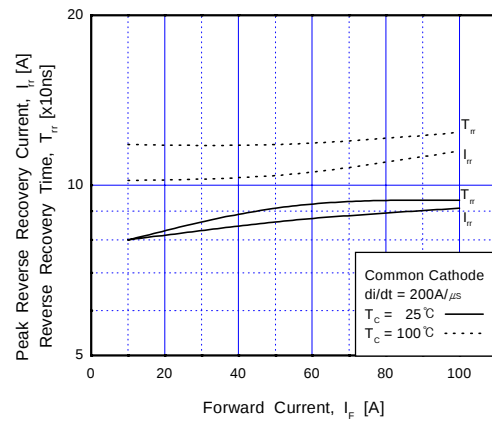


Fig 20. Reverse Recovery Characteristics

FMG1G100US60H

Technical drawing showing the front and side views of a rectangular electronic module with various components and dimensions.

Front View Dimensions:

- Overall width: 93 ± 0.5
- Overall height: 35 ± 0.6
- Top section height: 4 ± 0.6
- Bottom section height: 4 ± 0.6
- Central section height: 17 ± 0.6
- Left side feature: $2 - \varnothing 5.4 \pm 0.3$
- Internal spacing (top): 23 ± 0.5 , 23 ± 0.5 , 40 ± 0.5
- Internal spacing (bottom): 80 ± 0.5
- Mounting holes: $3 - M5$
- Component labels: C2E1, E2, C1, G2, E2, E1, G1

Side View Dimensions:

- Overall width: 90 ± 0.5
- Overall height: $22.3 - 0.6$
- Top section height: 7.7 ± 0.5
- Bottom section height: 5.8 ± 0.6
- Top section width: 16 ± 0.5 , 10 ± 0.5
- Bottom section width: 16 ± 0.5 , 10 ± 0.5
- Overall depth: 28.1 ± 0.5
- Overall depth (bottom): 32 ± 0.5

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